

SIZE	QTY	SYM	PLATED	TOL
0.065	8	+	YES	+/-0.003
0.035	18	X	YES	+/-0.003
0.07	4	□	NO	+/-0.003
0.01	18	◇	YES	+/-0.003
0.04	22	⊗	YES	+/-0.003
0.006	18	⊗	YES	+/-0.003
0.052	10	+ ^A	YES	+/-0.003

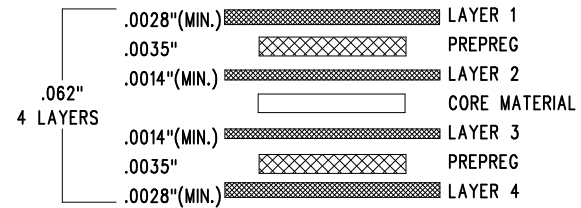
ADDITIONAL REQUIREMENT FOR PROTOTYPE FAB ONLY:

1. OUTGOING INSPECTION REPORT (BASED ON ACTUAL MEASUREMENTS AND CROSS SECTION).

ADDITIONAL REQUIREMENTS FOR PRODUCTION FAB ONLY:

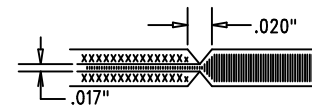
1. PROVIDE COMPLIANCE CERTIFICATES FOR RoHS, REACH AND CONFLICT-FREE MINERALS.
2. SOLDERABILITY BOARD WITH TEST RESULTS.
3. OUTGOING INSPECTION REPORT (BASED ON ACTUAL MEASUREMENTS AND CROSS SECTION).
4. VACUUM PACKED WITH DESICCANT.
5. FULL PANEL WITH NO REJECT.

LAYER STRUCTURE



NOTES: UNLESS OTHERWISE SPECIFIED

1. FAB PER IPC-A-600.
2. MATERIAL: -EPOXY FIBERGLASS, NEMA GRADE FR-4
-FINISHED THICKNESS TO BE 0.062" +/- .005"
-TOTAL OF 4 LAYERS WITH 2 OZ. FINISHED CU ON THE OUTER LAYERS AND 1 OZ. CU ON THE INNER LAYERS.
-FLAMMABILITY RATING: 94 V-0 MINIMUM.
3. SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
0.00" ARE PRIMARY DATUMS.
4. DRILLING: -DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
-HOLE LOCATION TOLERANCES ARE +/-0.003" IN RELATION TO CENTER
-FOR VIAS SIZE > 0.01", VIAS HOLES NEED TO BE PLUGGED AND COVERED WITH SOLDERMASK.
5. FINISH: -SMOBC USING LPI BOTH SIDES, COLOR GREEN(GLOSS).
-GOLD IMMERSION BOTH SIDES.
(LEAD FREE SOLDER CAN BE USED FOR PROTOTYPE)
-FOR SILKSCREEN: BOTH SIDES USE WHITE NON-CONDUCTIVE INK.
6. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE.
PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
7. PCBs ARE TO BE RoHS COMPLIANT.
8. SCORING FOR PANELIZED PCB:



UNLESS OTHERWISE SPECIFIED			
DIMENSIONS ARE IN INCHES TOLERANCES: 0.XX" = ±0.01" 0.XXX" = ±0.005" INTERPRET DIM AND TOL PER ASME Y14.5M-1994 THIRD ANGLE PROJECTION		www.analog.com TITLE: FABRICATION DRAWING I ² C TO CAN-PHYSICAL TRANSCEIVER	
SIZE	IC NO.	REV	
N/A	EVAL-LT3960-AZ	2	
			SHT 1 OF 1